

Title (en)  
Method and assembly for the generation of high energy microwave impulses

Title (de)  
Verfahren und Anordnung zur Erzeugung von Mikrowellen-Impulsen hoher Energie

Title (fr)  
Procédé et agencement de production d'impulsions de microondes à énergie élevée

Publication  
**EP 2397809 A3 20150121 (DE)**

Application  
**EP 11004608 A 20110607**

Priority  
DE 102010024214 A 20100617

Abstract (en)  
[origin: EP2397809A2] The method involves generating a pulse, particularly damped sinusoid-pulse by a pulse generator. The damped sinusoid-pulse is emitted by an antenna, where a plane arrangement (6,15) is exposed to an electromagnetic field of the pulse generated by the pulse generator in the area of the antenna. The plane arrangement has multiple conductor components. An independent claim is also included for an arrangement for generating microwave pulses of high energy, particularly those based on high power electromagnets technology.

IPC 8 full level  
**F41H 13/00** (2006.01); **H01Q 23/00** (2006.01)

CPC (source: EP US)  
**F41H 13/0068** (2013.01 - EP US); **F41H 13/0093** (2013.01 - EP US)

Citation (search report)

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Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)  
BA ME

DOCDB simple family (publication)  
**EP 2397809 A2 20111221; EP 2397809 A3 20150121; EP 2397809 B1 20160106**; DE 102010024214 A1 20111222;  
DE 102010024214 B4 20120503; US 2011309870 A1 20111222; US 8576109 B2 20131105

DOCDB simple family (application)  
**EP 11004608 A 20110607**; DE 102010024214 A 20100617; US 201113155424 A 20110608